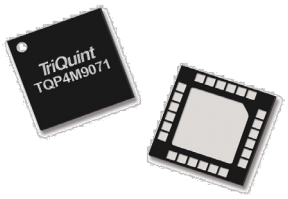
TQP4M9071

High Linearity 6-Bit, 31.5 dB Digital Step Attenuator

Applications

- Mobile Infrastructure
- LTE / WCDMA / CDMA / EDGE
- Test Equipments and Sensors
- IF and RF Applications
- General Purpose Wireless

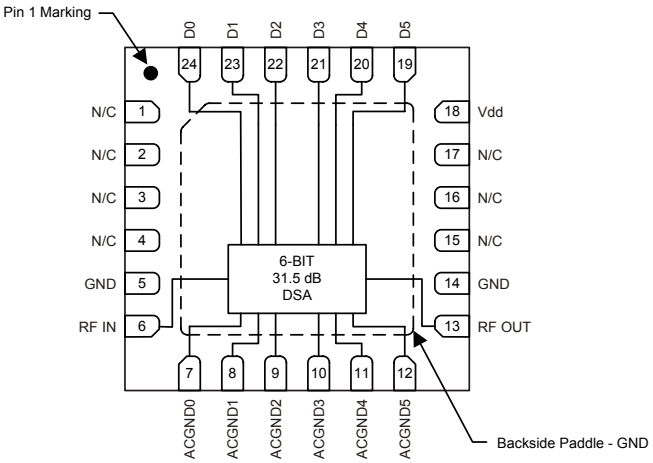


24-pin 4x4mm leadless QFN package

Product Features

- DC - 4 GHz
- 0.5 dB LSB Steps to 31.5 dB
- +57 dBm Input IP3
- 1.7 dB Insertion Loss @ 2.2 GHz
- TTL / CMOS Compatible Parallel Control Interface
- No requirement for external bypass capacitors for operation above 700 MHz
- 50 Ω Impedance
- +3.3V or +5V Supply Voltage

Functional Block Diagram



General Description

The TQP4M9071 is a high linearity, low insertion loss, 6-bit, 31.5 dB Digital Step Attenuator (DSA) operating over the DC-4 GHz frequency range. The digital step attenuator uses a single positive 3.3V or 5V supply and has a parallel control interface for changing attenuation states. This product maintains high attenuation accuracy over frequency and temperature. No external matching components are needed for the DSA. The product has an added feature of not requiring external AC ground capacitors for operation above 700 MHz.

The TQP4M9071 is available in a standard lead-free /green/RoHS-compliant 24-pin 4x4mm QFN package.

Also available from TriQuint is the TQP4M9072, a footprint and pin compatible DSA with a serial control interface.

Pin Configuration

Pin No.	Label
1, 2, 3, 4, 15, 16, 17	N/C
6	RF IN
7, 8, 9, 10, 11, 12	ACGND0-ACGND5
13	RF OUT
18	Vdd
19, 20, 21, 22, 23, 24	D0-D5
5, 14	GND
Backside Paddle	GND

Ordering Information

Part No.	Description
TQP4M9071	6-Bit, 31.5 dB DSA
TQP4M9071-PCB_ IF	0.04-0.5 GHz Evaluation Board
TQP4M9071-PCB_RF	0.7-4 GHz Evaluation Board

PCB includes USB control interface board, EVH.
Standard T/R size = 2500 pieces on a 13” reel.

Absolute Maximum Ratings

Parameter	Rating
Storage Temperature	−55 to 150°C
RF Input Power, 50Ω,T = 85°C	+28 dBm
V_{dd}, Power Supply Voltage	+7.0 V
V_{ctrl}, Control Bit Input Voltage	V_{dd} +1V

Operation of this device outside the parameter ranges given above may cause permanent damage.

Recommended Operating Conditions

Parameter	Min	Typ	Max	Units
Device Voltage (V_{DD})	+3.3	+5.0	+5.25	V
Case Temperature	−40		+85	°C

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

Test conditions: V_{DD}=+5 V, Temp= +25°C, 50Ω system, Mode 1, No external bypass capacitors used on pins 7-12.

Parameter	Conditions	Min	Typ	Max	Units
Operational Frequency Range	See Note 1 and 2.	DC		4000	MHz
Insertion Loss	1.0 GHz		1.3		dB
	2.0 GHz		1.6		dB
	2.2 GHz		1.7	2.2	dB
	3.5 GHz		2.1		dB
Return Loss	All States		17		dB
Accuracy Error	0.04-2.7 GHz, All States, Mode 2	± (0.3 + 3% of Atten. Setting) Max			dB
	0.7-2.7 GHz, All States, Mode 1 or Mode 2	± (0.3 + 3% of Atten. Setting) Max			dB
	2.7-3.5 GHz, All States, Mode 1 or Mode 2	± (0.4 + 4% of Atten. Setting) Max			dB
Attenuation Step	To be monotonic (Step Attenuation ≥ 0)	0	0.5		dB
Input IP3	Input = +15dBm / tone, All States		+57		dBm
Input P0.1dB	All States, DC-4 GHz		+30		dBm
Time $_{rise\ /\ fall}$	10% / 90% RF		90		ns
Time $_{On}$, Time $_{Off}$	50% CTL to 10% / 90% RF		100		ns
Supply Voltage, Vdd	See Note 3.		+5		V
Supply Current, Idd			1.4		mA

Notes:
1. In Mode 1 no external bypass capacitors are used and operating frequency is 0.7-4GHz. See detailed device description.
2. In Mode 2 external bypass capacitors are used and operating frequency may be extended to 0.04-4GHz. See detailed device description.
3. The product can be operated at lower Vdd of +3.3V with reduced performance.

Control Logic Requirements

Device has six TTL/CMOS compatible parallel control inputs to select attenuation states. Test conditions: +25°C, V_{dd} = +5V.

Parameter	Conditions	Min	Typical	Max	Units
Low State Input Voltage		0		0.8	V
High State Input Voltage		2		Vdd	V
Low State Current	V_{ctrl}=+0.8V		5	uA	uA
High State Current	V_{ctrl}=+5V		50	uA	uA

Detailed Device Description

The TQP4M9071 is a high linearity, low insertion loss, wideband, 6-bit, 31.5 dB digital step attenuator. The digital step attenuator uses a single 3.3V or 5V supply and has a parallel control interface for changing attenuation states. This product maintains high attenuation accuracy over frequency and temperature. The product does not require any external bypass capacitors on AC ground pins for operation above 700 MHz. The DSA performance remains unchanged for frequency range 0.7 – 4 GHz in either Mode 1 or Mode 2. The operating frequency may be extended to low frequency range (0.04 – 0.7 GHz) with external bypass capacitors on AC ground pins (ACGND0-ACGND5).

Further assistance may be requested from TriQuint Applications Engineering:
Email: **sjcapplications.engineering@triquint.com**

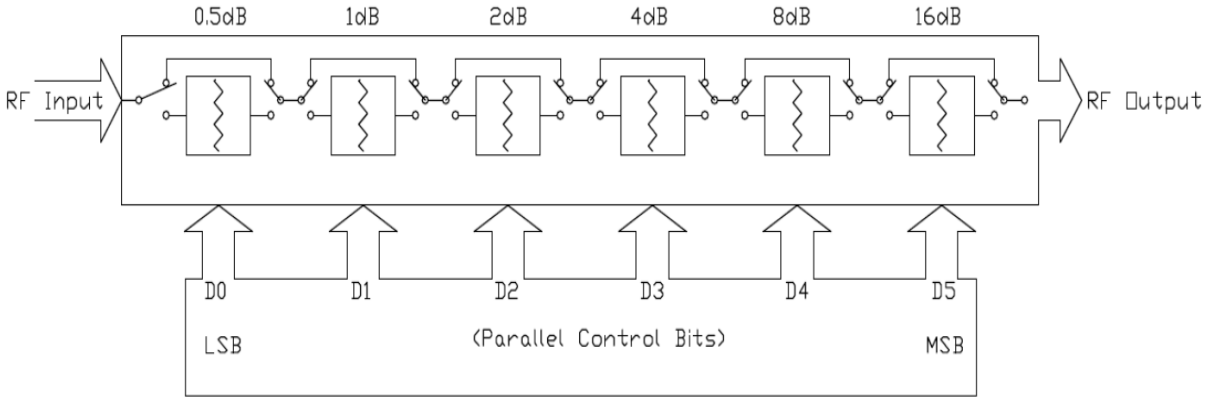
Control Logic Truth Table

Test conditions: +25°C, V_{dd} = +5V

LSB			Control Bits		MSB	Attenuation
D0	D1	D2	D3	D4	D5	State
1	1	1	1	1	1	Reference : IL
0	1	1	1	1	1	0.5 dB
1	0	1	1	1	1	1 dB
1	1	0	1	1	1	2 dB
1	1	1	0	1	1	4 dB
1	1	1	1	0	1	8 dB
1	1	1	1	1	0	16 dB
0	0	0	0	0	0	31.5 dB

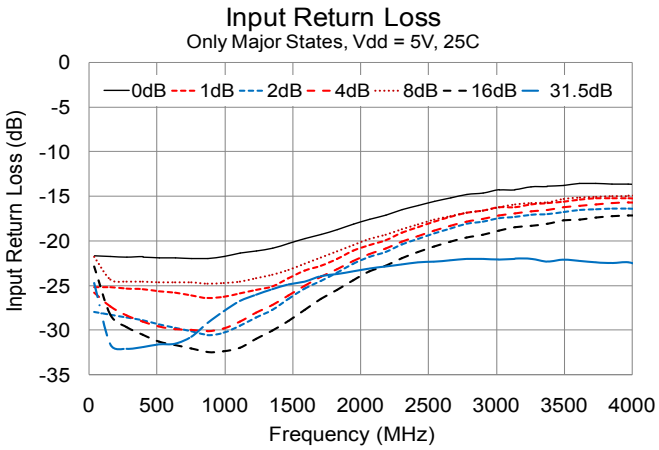
Any combination of the possible 64 states will provide an attenuation of approximately the sum of bits selected

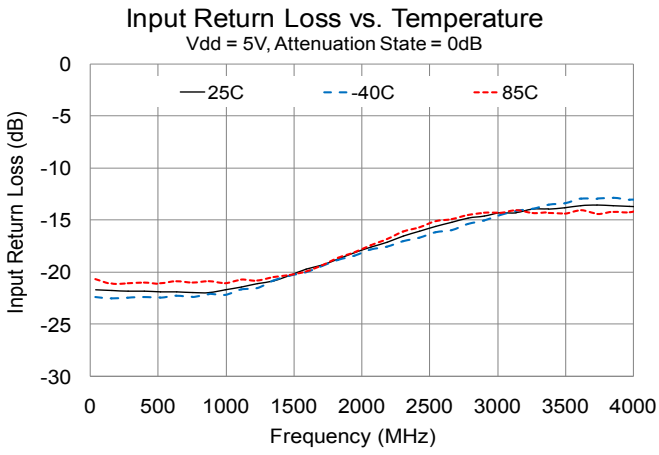
Functional Schematic Diagram

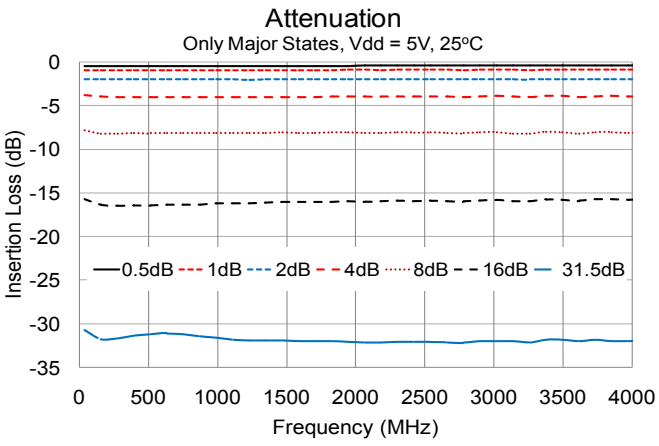


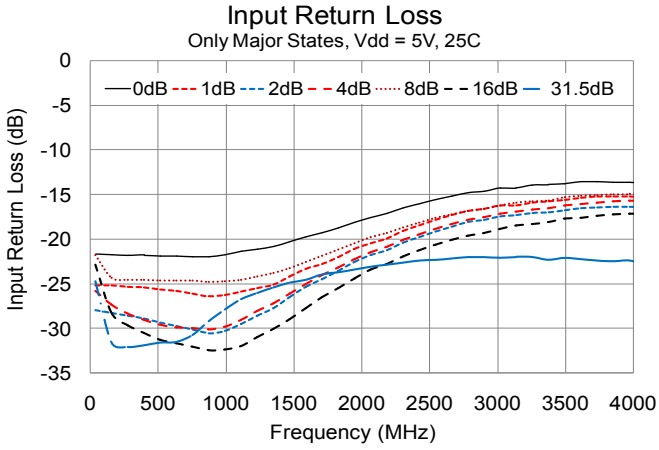
Typical Performance Plots

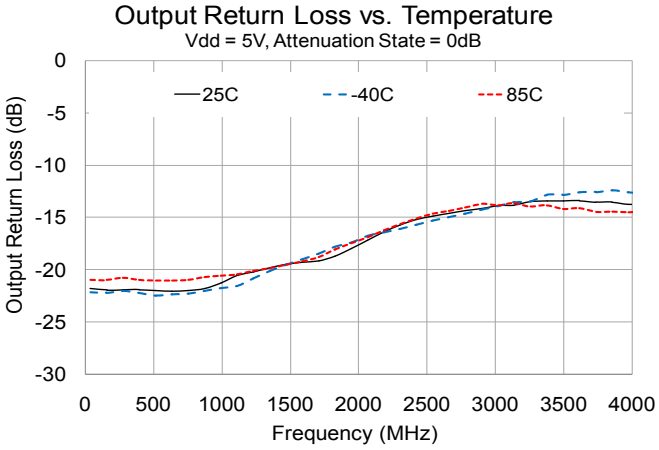
Performance plots data is measured using Bias Tee on RF ports in Mode 2 configuration. Mode 2 operation is required to obtain performance at frequencies lower than 0.7 GHz. For frequency range 0.7 - 4.0 GHz, data is identical in Mode 1 and Mode 2.



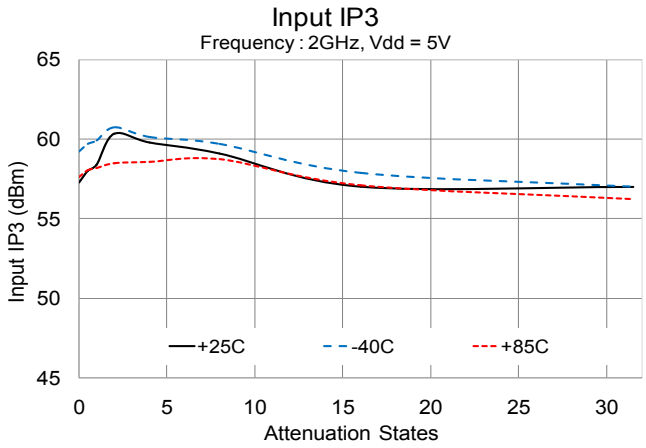


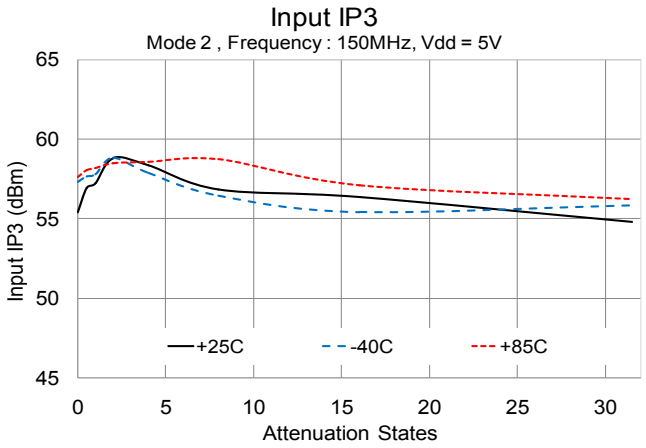


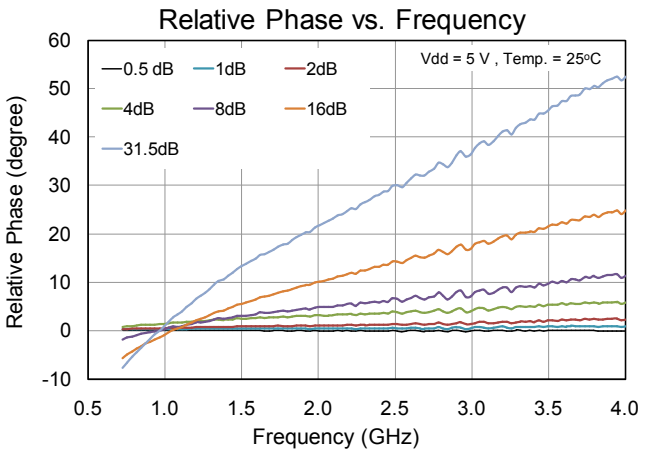


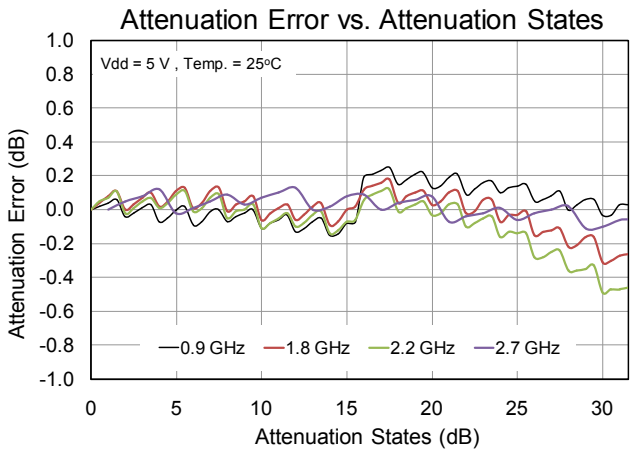


Typical Performance Plots



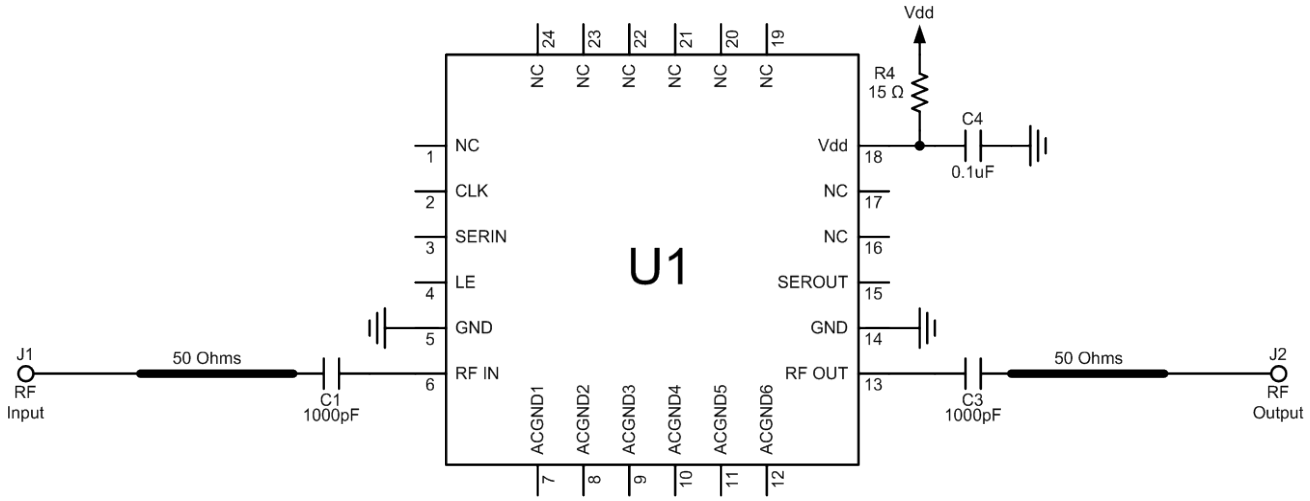






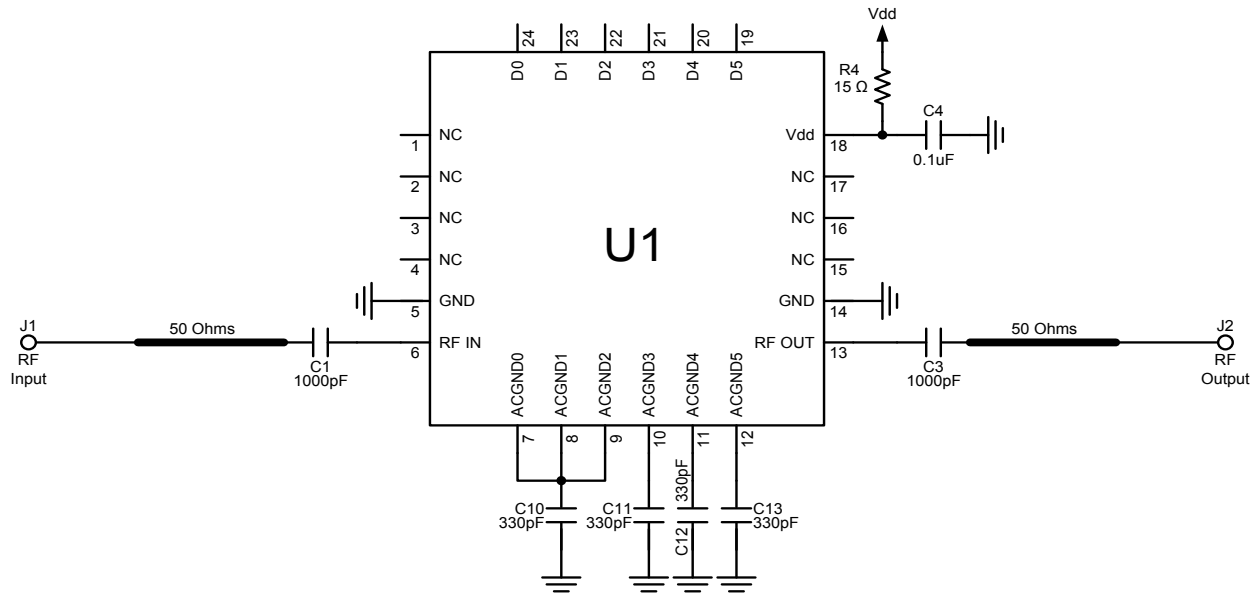
Mode 1: 0.7 – 4.0 GHz Operation (TQP4M9071-PCB_RF)

No external bypass capacitors required. There are 0.2 pF shunt capacitors (C5 and C7) next to RF connectors, on the application board, to resonate out the RF connector parasitic. These shunt capacitors are not required in the final application circuit.

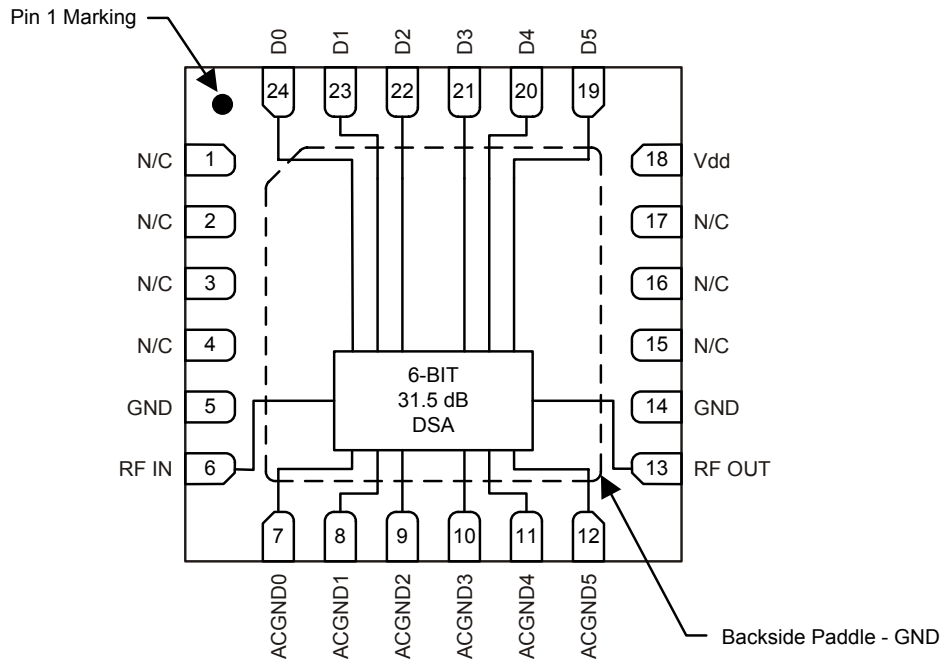


Mode 2: 0.04 – 4.0 GHz Operation (TQP4M9071-PCB_IF)

External bypass capacitors required on ACGND0 - ACGND5 pins. For improved operation below 0.1 GHz, blocking and bypass capacitors values can be increased to 10 nF. This circuit configuration can also be used for operation up to 4 GHz. The DSA performance remains unchanged for frequency range 0.7 – 3.5 GHz in either Mode 1 or Mode 2. There are 0.2 pF shunt capacitors (C5 and C7) next to RF connectors, on the application board, to resonate out the RF connector parasitic. These shunt capacitors are not required in the final application circuit.



Pin Configuration and Description



Pin No.	Label	Description
6	RF IN	RF Input , DC voltage present, blocking capacitor required
7	ACGND0	AC ground for extended low frequency operation option
8	ACGND1	AC ground for extended low frequency operation option
9	ACGND2	AC ground for extended low frequency operation option
10	ACGND3	AC ground for extended low frequency operation option
11	ACGND4	AC ground for extended low frequency operation option
12	ACGND5	AC ground for extended low frequency operation option
13	RF OUT	RF Output , DC voltage present, blocking capacitor required
18	V_{dd}	Supply Voltage, bypass capacitor required close to the pin
19	D5	16 dB attenuation control bit
20	D4	8 dB attenuation control bit
21	D3	4 dB attenuation control bit
22	D2	2 dB attenuation control bit
23	D1	1 dB attenuation control bit
24	D0	0.5 dB attenuation control bit
1, 2, 3, 4, 15, 16, 17	N/C	No electrical connection. Land pads should be provided for PCB mounting integrity.
5, 14	GND	These pins must be connected to RF/DC ground
Backside Paddle	GND	RF/DC ground. Use recommended via pattern to minimize inductance and thermal resistance. See PCB Mounting Pattern for suggested footprint.

Applications Information

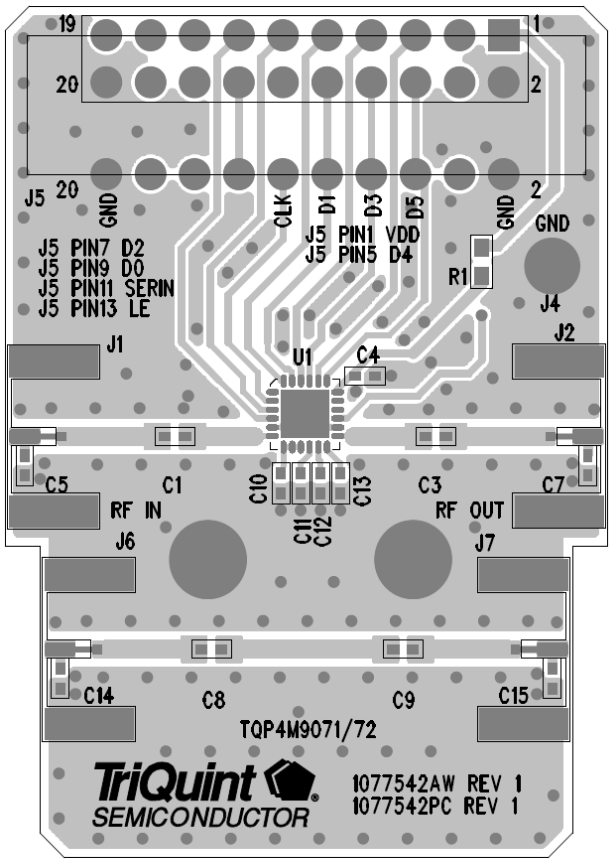
PC Board Layout

Top RF layer is .020" Rogers-4003, ϵ_r = 3.45, 4 total layers (0.062" thick) for mechanical rigidity. Metal layers are 1-oz copper. Microstrip line details: width = .040", spacing = .020".

External DC blocking capacitors are required on RFin and RFout pins of the device. The supply voltage for the DSA is supplied externally through pin Vdd. Frequency bypassing for this pin is supplied by surface mount capacitor 0.1 uF (C4). This capacitor is placed close to the device pin in the board layout. To ensure application circuit is compatible with different standard power supplies, 15 Ω (R1) dropping resistor is highly recommended on Vdd supply line.

RF layout is critical for getting the best performance RF trace impedance needs to be 50 ohm. For measuring the actual device performance on connectorized PC board, input losses due to RF traces need to be subtracted from the data measured through SMA connectors. The calibration microstrip line J6-J7 estimates the PCB insertion loss for removal from the evaluation board measured data. All data shown on the datasheet are de-embedded up to the device input/output pins.
The PC board is designed to test using USB control interface board, Evaluation Board Host (EVH). Each TQP4M9071 evaluation board is supplied with the EVH board, USB cable and EVH graphical user interface (EVH GUI) to change attenuation states. Manual for using EVH and Application note describing the EVH are also available. Refer to TriQuint's website for more information

The pad pattern shown has been developed and tested fo optimized assembly at TriQuint Semiconductor. The PCI land pattern has been developed to accommodate lea and package tolerances. Since surface mount processe vary from company to company, careful proces development is recommended.



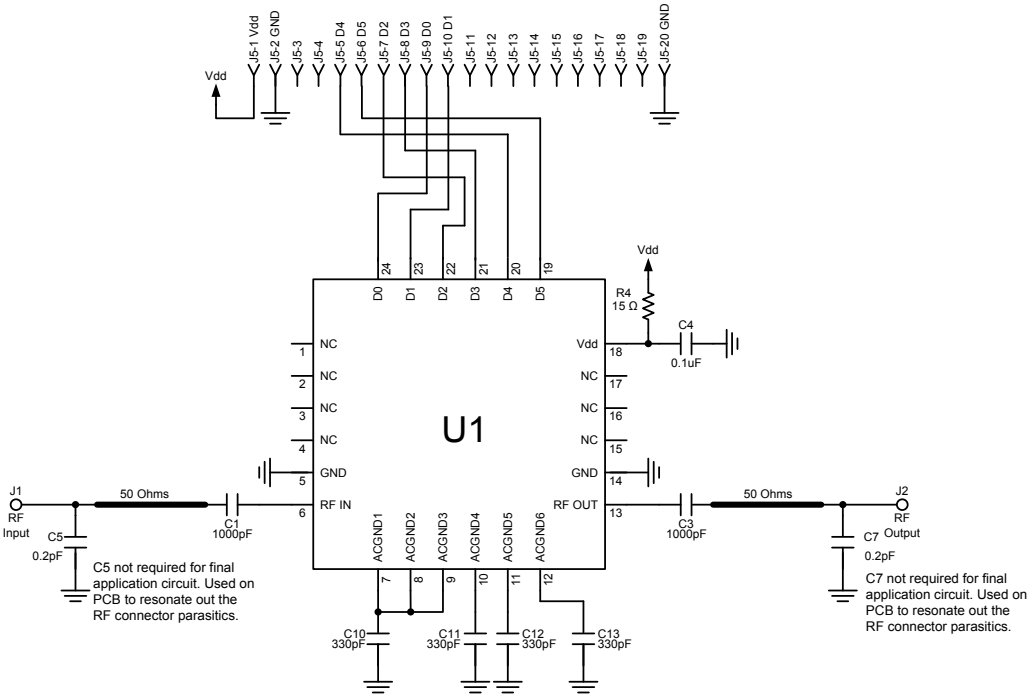
Bill of Material: TQP4M9071-PCB_RF

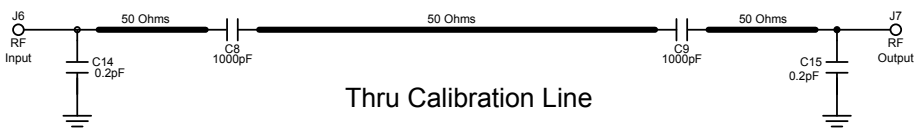
Reference Desg.	Value	Description	Manufacturer	Part Number
U1		High Linearity 6-Bit, 31.5dB, DSA	TriQuint	TQP4M9071
C4	0.1 uF	Cap, Chip, 0402, 16V, 20%	various	
C1,C3,C8, C9	1000 pF	Cap, Chip, 0402, 50V, 10%	various	
R1	15 Ω	Res, Chip, 0402, 1/16W, 5%	various	
C10, C11, C12, C13	DNP	Do Not Place	various	

Bill of Material: TQP4M9071-PCB_IF

Reference Desg.	Value	Description	Manufacturer	Part Number
U1		High Linearity 6-Bit, 31.5dB, DSA	TriQuint	TQP4M9071
C4	0.1 uF	Cap, Chip, 0402, 16V, 20%	various	
C1,C3,C8, C9	1000 pF	Cap, Chip, 0402, 50V, 10%	various	
R1	15 Ω	Res, Chip, 0402, 1/16W, 5%	various	
C10, C11, C12, C13	330 pF	Cap, Chip, 0402, 50V, 10%	various	

TQP4M9071-PCB_RF/IF Schematic

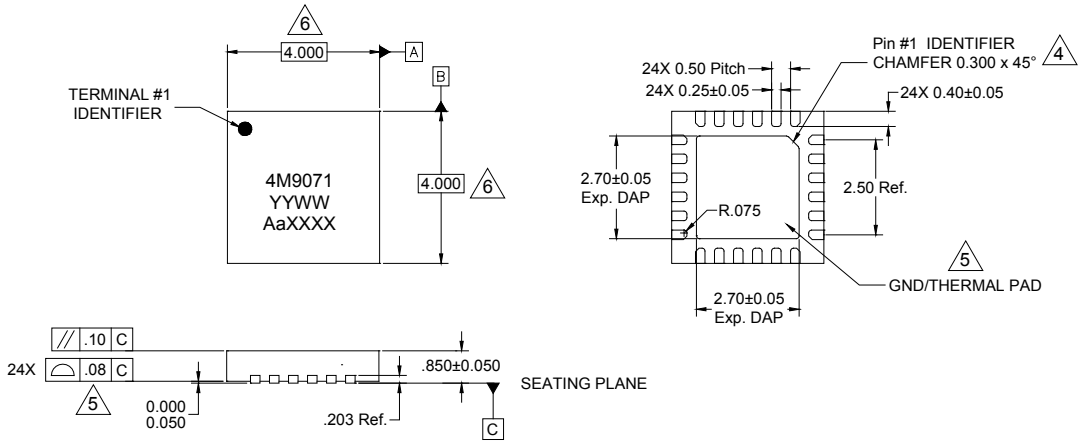




Thru Calibration Line

Package Marking and Dimensions

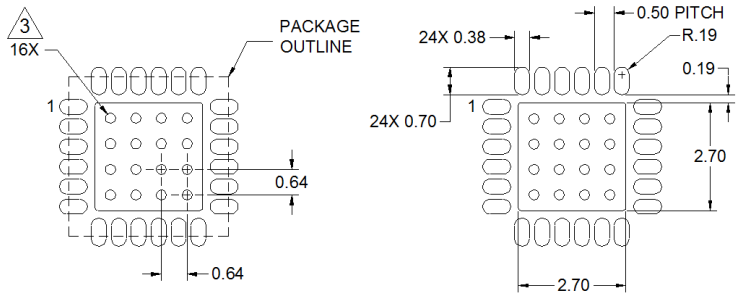
Marking: Part number – 4M9071
Year/week code – YYWW
Assembly code– AaXXXX



Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Except where noted, this part outline conforms to JEDEC standard MO-220, Issue E (Variation VGGC) for thermally enhanced plastic very thin fine pitch quad flat no lead package (QFN).
3. Dimension and tolerance formats conform to ASME Y14.4M-1994.
4. The terminal #1 identifier and terminal numbering conform to JESD 95-1 SPP-012.
5. Co-planarity applies to the exposed ground/thermal pad as well as the contact pins.
6. Package body length/width does not include plastic flash protrusion across mold parting line.

PCB Mounting Pattern



COMPONENT SIDE

Notes:

1. All dimensions are in millimeters. Angles are in degrees.
2. Use 1 oz. copper minimum for top and bottom layer metal.
3. Vias are required under the backside paddle of this device for proper RF/DC grounding and thermal dissipation. We recommend a 0.35mm (#80/.0135") diameter bit for drilling via holes and a final plated thru diameter of 0.25 mm (0.10”).
4. Ensure good package backside paddle solder attach for reliable operation and best electrical performance.

Product Compliance Information

ESD Sensitivity Ratings

Caution! ESD-Sensitive Device

ESD Rating:	Class 1B
Value:	Passes ≥ 500V to <1000V
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114

ESD Rating:	Class IV
Value:	Passes ≥ 1000 V
Test:	Charged Device Model (CDM)
Standard:	JEDEC Standard JESD22-C101

MSL Rating

MSL Rating:	Level 1
Test:	+260 °C convection reflow
Standard:	JEDEC standard IPC/JEDEC J-STD-020

Solderability

Compatible with both lead-free (260 °C max. reflow temp.) and tin/lead (245 °C max. reflow temp.) soldering processes.

Package lead plating: Annealed Matte Tin over Copper

RoHs Compliance

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A ($C_{15}H_{12}Br_4O_2$) Free
- PFOS Free
- SVHC Free
- Lead Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

Web: www.triquint.com **Tel:** +1.503.615.9000
Email: info-sales@triquint.com **Fax:** +1.503.615.8902

For technical questions and application information:

Email: sjcapplications.engineering@triquint.com

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